

SD103ATHRU SD103C

SMALL SIGNAL SCHOTTKY DIODES

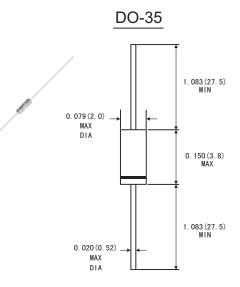
FEATURES

- · For general purpose applications
- The SD103 series is a Metal-on-silicon junction Schottky barrier device which is protected by a PN junction guard ring. The low forward voltage drop and fast switching make it ideal for protection of MOS devices, steering, biasing, and coupling diodes for fast switching and low logic le vel applications. Other applications are click suppressions, efficient full wavebridges in telephone subsets, and blocking diodes in re chargeable low voltage battery systems.
- These diodes are also available in the MiniMELF case with the type designation LL103A to thru LL103C.
- · High temperature soldering guaranteed:260°C/10 seconds at terminals
- · Component in accordance to RoHS 2011/65/EU

MECHANICAL DATA

· Case: DO-35 Glass case

· Weight: Approx. 0.13 gram



Dimensions in inches and (millimeters)

ABSOLUTE RATINGS (LIMITING VALUES)

		Symbols	Value	Units		
Peak Reverse Voltage	SD103A SD103B SD103C	Vrrm Vrrm Vrrm	40 30 20	>		
Power Dissipation (infinite Heat Sink)		Ptot	400 ¹)	mW		
Maximum Single cycle surge 60Hz sine wave		IFSM	15	Α		
Junction temperature		TJ	125	°C		
Storage Temperature Range		Тѕтс	-55 to+150	°C		
1) Valid provided that leads at a distance of 4mm from case are kept at ambient temperature						

ELECTRICAL CHARACTERISTICS

(Ratings at 25°C ambient temperature unless otherwise specified)

	Symbols	Min.	Тур.	Max.	Unis	
Leakage current at V _R =30V SD103A V _R =20V SD103B V _R =10V SD103C	IR IR IR			5 5 5	μΑ μΑ μΑ	
Forward voltage drop at I _F =20mA I _F =200mA	VF VF			0.37 0.6	V V	
Junction Capacitance at V _R =0V ,f=1MHz	Cı		50		pF	
Reverse Recovery time at I _F =I _R =50mA,recover to 200mA recover to 0.1 I _R	trr		10		ns	
Thermal resistance, junction to Ambient	RθJA			300 1)	°C/W	
1) Valid provided that electrodes are kept at ambient temperature						

RATINGS AND CHARACTERISTICS CURVES SD103A THRU SD103C

Figure 1. Typical variation of fwd.current vs.fwd. Voltage for primary conduction through the schottky barrier

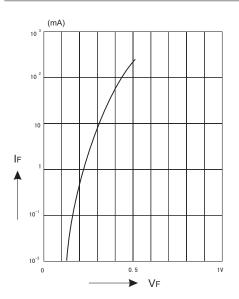
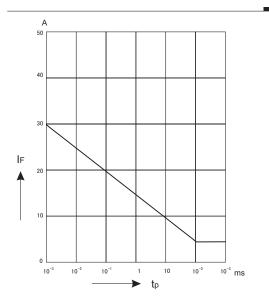


Figure 3. Typical non repetitive forward surge current versus pulse width



JINAN JINGHENG ELECTRONICS CO., LTD.

Figure 2. Typical high current forward conduction curve tp=300ms,duty cycle=2%

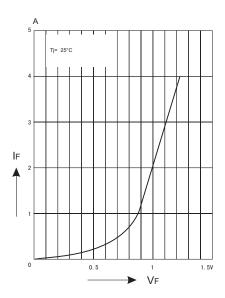
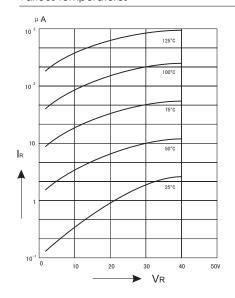


Figure 4. Typical variation of reverse current at various temperatures



3-2

HTTP://WWW.JINGHENGGROUP.COM

Figure 5. Blocking voltage deration versus temperature at various average forward currents

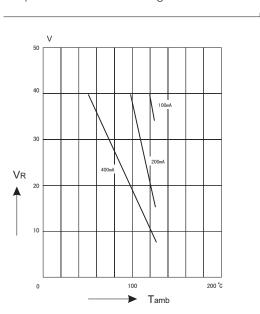


Figure 6. Typical capacitance versus reverse voltage

